



TotalEnergies

Refining & Chemicals
Polymers

Description

Aceso® Lumicene® MR10MM0 S01 is a metallocene random copolymer polypropylene with a Melt Flow Index of 10(*) g/10 min specially developed for the extrusion of film and injection stretch blow moulding for the medical application, to the exclusion of implants.

Aceso® Lumicene MR10MM0 S01 differs from the other random copolymers by outstanding organoleptic properties combined with ultra low extractables.

Characteristics

	Method	Unit	Typical Value
Rheological properties			
Melt Flow Index 230°C/2.16 kg	ISO 1133	g/10 min	10 (*)
Mechanical properties			
Tensile Strength at Yield	ISO 527-2	MPa	26
Elongation at Yield	ISO 527-2	%	10
Tensile modulus	ISO 527-2	MPa	950
Flexural modulus	ISO 178	MPa	900
Izod Impact Strength (notched) at 23°C	ISO 180	kJ/m ²	4.5
Thermal properties			
Melting Point	ISO 3146	°C	137
Other physical properties			
Density	ISO 1183	g/cm ³	0.902
Bulk Density	ISO 1183	g/cm ³	0.525

(*) MFI 10 in metallocene catalyst system processes like MFI 8 in standard Ziegler Natta catalyst system.

Handling and storage

Please refer to the safety data sheet (SDS) for handling and storage information. It is advisable to convert the product within one year after delivery provided storage conditions are used as given in the SDS of our product. SDS may be obtained from the website: www.polymers.totalenergies.com.

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